NE/SE5018/5019

DESCRIPTION

The NE/SE5018/19 is a complete 8-bit digital-to-analog converter subsystem on one monolithic chip. The data inputs have input latches which are controlled by a latch enable pin. The data and latch enable inputs are ultra-low loading for easy interfacing with all logic systems. The latches appear transparent when the $\overline{\text{LE}}$ input is in the low state. When $\overline{\text{LE}}$ goes high, the input data present at the moment of transition is latched and retained until $\overline{\text{LE}}$ again goes low. This feature allows easy compatibility with most microprocessors.

The chip also comprises a stable voltage reference (5V nominal) and high slew rate buffer amplifier. The voltage reference may be externally trimmed with a potentiometer for easy adjustment of full-scale while maintaining a low temperature coefficient.

The output of the buffer amplifier may be offset so as to provide bipolar as well as unipolar operation.

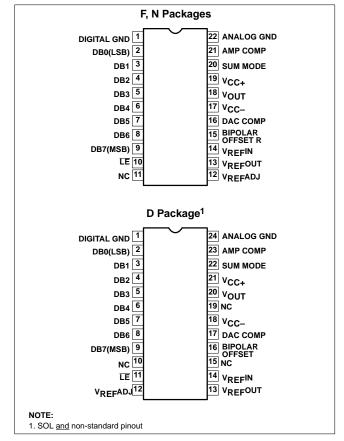
FEATURES

- 8-bit resolution
- Input latches
- Low-loading data inputs
- On-chip voltage reference
- Output buffer amplifier
- Accurate to ± LSB (0.19%)
- Monotonic to 8 bits
- Amplifier and reference both short-circuit protected
- Compatible with 8085, 6800 and many other μPs

APPLICATIONS

- Precision 8-bit D/A converters
- A/D converters
- Programmable power supplies
- Test equipment
- Measuring instruments
- Analog-digital multiplication

PIN CONFIGURATIONS

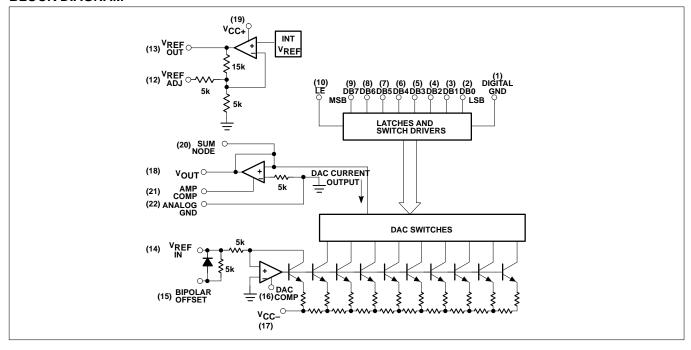


ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #
22-Pin Ceramic Dual In-Line Package (CERDIP)	0 to +70°C	NE5018/5019F	0585B
22-Pin Ceramic Dual In-Line Package (CERDIP)	-55°C to +125°C	SE5018/5019F	0585B
22-Pin Plastic Dual In-Line Package (DIP)	0 to +70°C	NE5018/5019N	0409B
22-Pin Plastic Dual In-Line Package (DIP)	-55°C to +125°C	SE5018/5019N	0409B
24-Pin Small Outline Large (SOL) Package	0 to +70°C	NE5018/5019D	0173D

NE/SE5018/5019

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER	RATING	UNIT
V _{CC} +	Positive supply voltage	18	V
V _{CC} -	Negative supply voltage	-18	V
V _{IN}	Logic input voltage	0 to 18	V
V _{REF IN}	Voltage at V _{REF} input	12	V
V _{REF} ADJ	Voltage at V _{REF} adjust	0 to V _{REF}	V
V _{SUM}	Voltage at sum node	12	V
I _{REF SC}	Short-circuit current to ground at V _{REF OUT}	Continuous	
loutsc	Short-circuit current to ground or either supply at V _{OUT}	Continuous	
P _D	Maximum power dissipation, T _A =25°C (still-air) ¹		
	F package	1740	mW
	N package	2190	mW
	D package	1600	mW
T _A	Operating temperature range		
	SE5018	-55 to +125	°C
	NE5018	0 to +70	°C
T _{STG}	Storage temperature range	-65 to +150	°C
T _{SOLD}	Lead soldering temperature		
	(10 seconds)	300	°C

1. Derate above 25°C at the following rates:

F package at 13.9mW/°C N package at 17.5mW/°C

D package at 12.8mW/°C

NE/SE5018/5019

DC ELECTRICAL CHARACTERISTICS

 $V_{CC}\text{+=+15V},\ V_{CC}\text{-=-15V},\ SE5018.\ \text{-}55^{\circ}C \leq T_{A} \leq 125^{\circ}C,\ NE5018.\ 0^{\circ}C \leq T_{A} \leq 70^{\circ}C,\ unless\ otherwise\ specified.\ ^{1}\ Typical\ values\ are\ specified\ at\ 25^{\circ}C.$

	VCC-=-13V, 3E301633 CS1AS123 C		N	E/SE50	18	NE/SE5019				
SYMBOL	PARAMETER	TEST CONDITIONS	Min Typ		Max	Min Typ		Max	UNIT	
	Resolution		8	8	8	8	8	8	Bits	
	Monotonicity		8	8	8	8	8	8	Bits	
	Relative accuracy				±0.19			±0.1	%FS	
V _{CC} +	Positive supply voltage		11.4	15		11.4	15		V	
V _{CC} -	Negative supply voltage		-11.4	-15		-11.4	-15		V	
V _{IN(1)}	Logic "1" input voltage	Pin 1=0V	2.0			2.0			V	
V _{IN(0)}	Logic "0" input voltage	Pin 1=0V			0.8			0.8	V	
I _{IN(1)}	Logic "1" input current	Pin 1=0V, 2V <v<sub>IN<18V</v<sub>		0.1	10		0.1	10	μΑ	
I _{IN(0)}	Logic "0" input current	Pin 1=0V, -5V <v<sub>IN<0.8V</v<sub>		-2.0	-10		-2.0	-10	μΑ	
V _{FS}	Full-scale output	Unipolar mode, V _{REF} =5.000V,	9.50		10.5	9.50		10.5	V	
		all bits high, T _A =25°C						1		
+V _{FS}	Full-scale output	Bipolar mode, V _{REF} =5.000V	4.75		5.25	4.75		5.25	V	
TVFS	Full-scale output	all bits high, T _A =25°C								
-V _{FS}	Negative full scale	Bipolar mode, V _{REF} =5.000V,	-5.25		-4.75	-5.25		-4.75	V	
		all bits low, T _A =25°C								
V _{ZS}	Zero-scale Output	Unipolar mode, V _{REF} =5.000V	-30		+30	-30		+30	mV	
		all bits low, T _A =25°C								
I _{OS}	Output short circuit current	T _A =25°C V _{OUT} =0V		15	40		15	40	mA	
PSR+ _(OUT)	Output power supply rejection (+)	V-=-15V, 13.5V≤V+≤16.5V, external V _{REF IN} =5.000V		0.001	0.01		0.001	0.01	%FS %VS	
PSR- _(OUT)	Output power supply rejection (-)	V+=-15V, -13.5V≤V-≤-16.5V, external V _{REF IN} =5.000V		0.001	0.01		0.001	0.01	%FS %VS	
TC _{FS}	Full-scale temperature coefficient	V _{REF IN} =5.000V		20			20		ppm/°C	
TC _{ZS}	Zero-scale temperature coefficient			5			5		ppm/°C	
I _{REF}	Reference output current				3			3	mA	
I _{REFSC}	Reference short circuit current	T _A =25°C V _{REF OUT} =0V		15	30		15	30	mA	
PSR+ _(REF)	Reference power supply rejection (+)	V-=-15V, 13.5V≤V+≤16.5V, I _{REF} =1.0mA		0.003	0.01		0.003	0.01	%VR/%VS	
PSR-(REF)	Reference power supply rejection (-)	V+=-15V, -13.5V≤V-≤16.5V,		0.003	0.01		0.003	0.01	%VR/%VS	
V _{REF}	Reference voltage	I _{REF} =1.0mA T _A =25°C	4.9	5.0	5.25	4.9	5.0	5.25	V	
TC _{REF}	Reference voltage temperature coefficient	I _{REF} =1.0mA		60			60		ppm/°C	
Z _{IN}	DAC V _{REF IN} input impedance	I _{REF} =1.0mA, T _A =25°C	4.15	5.0	5.85	4.15	5.0	5.85	kΩ	
I _{CC} +	Positive supply current	V _{CC} +=15V		7	14		7	14	mA	
I _{CC} -	Negative supply current	V _{CC} -=-15V		-10	-15		-10	-15	mA	
P _D	Power dissipation	I _{REF} =1.0mA, V _{CC} =±15V		255	435		255	435	mW	

NOTES:

1. Refer to Figure 1.

August 31, 1994 753

NE/SE5018/5019

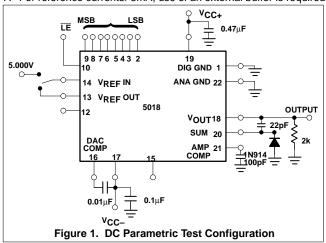
AC ELECTRICAL CHARACTERISTICS¹

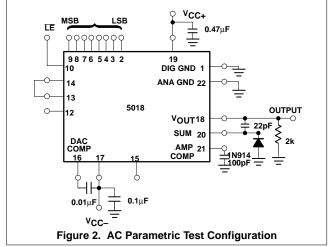
 $V_{CC}=\pm 15V,\, T_A=25^{\circ}C$

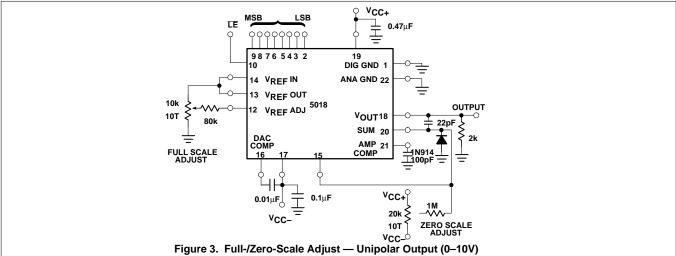
SYMBOL	PARAMETER	то	FROM	TEST CONDITIONS	NE/SE5018/19			UNIT
		10		TEST CONDITIONS	Min	Тур	Max	
t _{SLH}	Settling time	±1/2LSB	Input	All bits low-to-high ²		1.8		μs
t _{SHL}	Settling time	±1/2LSB	Input	All bits high-to-low ³		2.3		μs
t _{PLH}	Propagation delay	Output	Input	All bits switched low-to-high ²		300		ns
t _{PHL}	Propagation delay	Output	Input	All bits switched high-to-low ³		150		ns
t _{PLSB}	Propagation delay	Output	Input	1 LSB change ^{2, 3}		150		ns
t _{PLH}	Propagation delay	Output	ΙE	Low-to-high transition ⁴		300		ns
t _{PHL}	Propagation delay	Output	LE	High-to-low transition ⁵		150		ns
t _S	Setup time	LE	Input	1, 6	100			ns
t _H	Hold time	Input	LE	1, 6	50			ns
t _{PW}	Latch enable pulse width			1, 6	150			ns

NOTES:

- 1. Refer to Figure 2.
- 2. See Figure 5.
- 3. See Figure 6.
- 4. See Figure 7.
- 5. See Figure 8.
- 6. See Figure 9.
- 7. For reference currents>3mA, use of an external buffer is required.

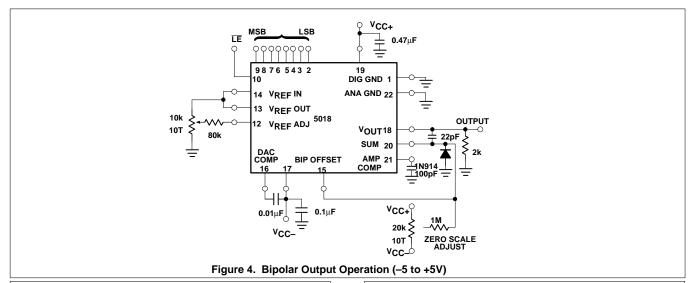


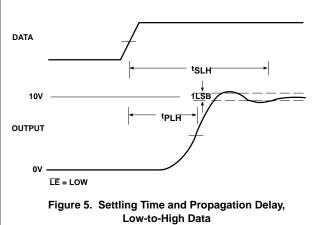


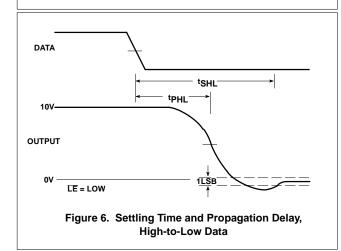


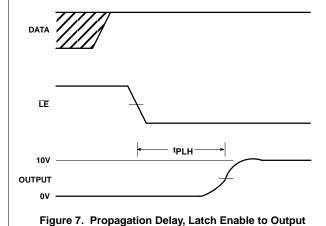
August 31, 1994 754

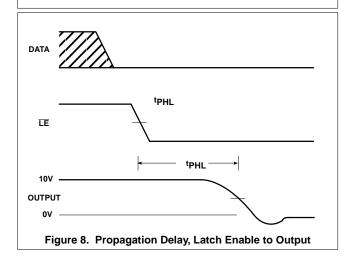
NE/SE5018/5019



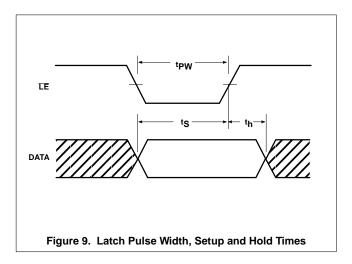








NE/SE5018/5019



August 31, 1994 756